Voltage Level Translation Guide







Translation Guide



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Introduction

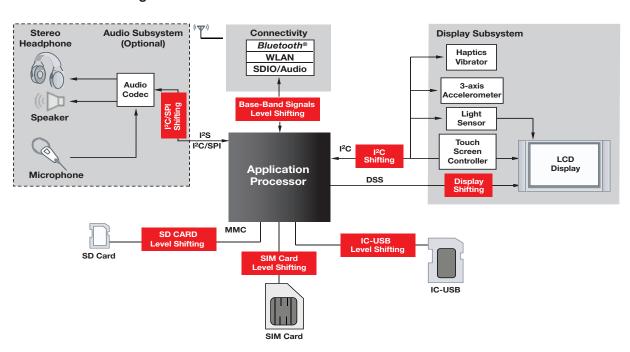
In today's complex and high-performance system environment, higher levels of functional integration have led to lower power consumption CMOS process technologies operating at lower supply voltage levels. The ability to mix, match and support the simultaneous use of different operating supply voltage levels on the same circuit board has led to the need for voltage-level translation.

To remedy this problem of logic-threshold incompatibility between the driver output thresholds and receiver input thresholds, a voltage-level translator device from Texas Instruments should be used to accomplish this.

To assist circuit design and system engineers with their operating speed and lower-operating voltage level-translation needs, Texas Instruments (TI) offers a comprehensive voltage translation portfolio including dual-supply level translators; auto-direction sensing translators for both push-pull buffered and open-drain applications; and hybrid application-specific translators optimized for today's constantly emerging signal standards. Translation devices are needed in various markets such as consumer electronic, portable. computing, and networking applicationswherever the need exists to interface lower operating processors with higher operating legacy peripherals.

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Portable Electronic Block Diagram

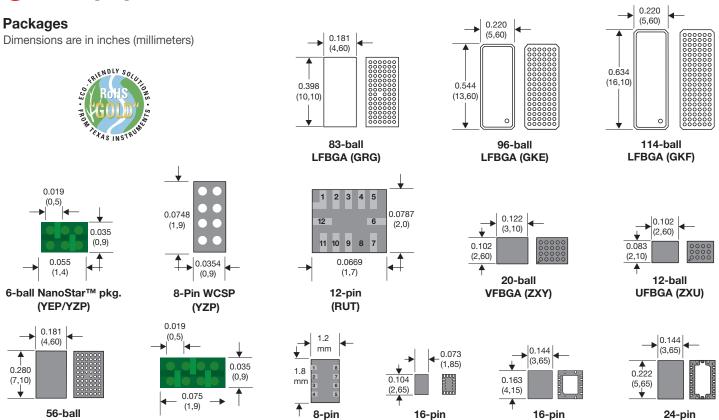


Packaging

VFBGA (GQL)

8-ball NanoStar™ pkg.

(YEP/YZP)



μQFN (DQM)

QFN (RSV)

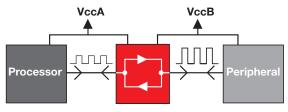
QFN (RGY)

QFN (RHL)

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Four Classes of Voltage Translators

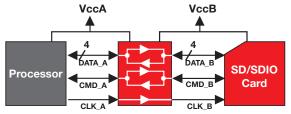
Auto-direction sensing translators



TXB010x and TXB030x

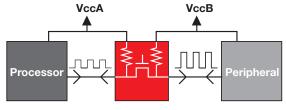
Voltage translators

Application-specific translators (memory card and SIM card interfaces)



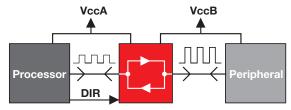
TXS02xxx and TXS45xx

Auto-direction sensing translators for open-drain applications



TXS010x/E and TXS030x

Dual-supply configurable translators



SN74AVCxT45/245/234/244 and SN74LVCxT45/245

Auto-Direction Sensing Translators Portfolio

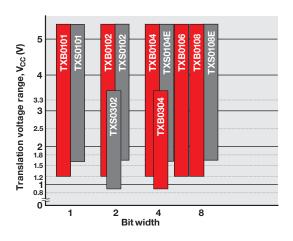
Key Features

- Auto-direction sensing no direction control signal needed
- Automatic reconfigurable I/O buffers

 each I/O port is configured

 as both an input and an output
- Integrated pull-up resistors provides modest DC-bias and current sourcing capabilities while saving BOM costs
- Output slew-rate control circuitry — edge-rate accelerator circuitry detects and speeds up AC-transitions to maintain fast data rate throughput
- V_{CC} isolation feature if either V_{CC} input is at GND, all outputs are in the high impedance state
- Highly integrated ESD protection ±15-kV ESD protection on the B port
- Devices ending in E suffix include integrated IEC 61000-4-2 ESD protection.

TI's auto-direction sensing translation devices are ideal for point-to-point topologies when interfacing devices may be operating at different interface voltage levels. They improve connectivity between next-generation processors and peripheral devices by eliminating the requirement for direction-control signals used by traditional voltage-level translation devices. This decreases the control software complexity while saving valuable GPIO signals on core processors.



Auto direction-sensing translators.



Auto-Direction Sensing Translators

Bidirectional Auto Direction Sensing Translators with 0.9 V Support

TXB030x

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXB030x

Key Features

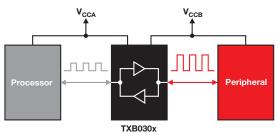
- Optimized for push-pull applications
- Fully symmetric supply voltages:
 0.9 V to 3.6 V on both A-port
 and B-port
- V_{CC} isolation feature If either V_{CC} input is at GND, all outputs are in the high-impedance state
- OE input circuit referenced to V_{CCA}
- Low power consumption, 5-μA max I_{CC}
- 8-kV Human-Body Model (HBM)

Applications

- Cell phones
- Tablets
- · Portable GPS devices
- Bluetooth® headsets
- General portable consumer applications

These non-inverting translators use two separate configurable power-supply rails. As voltage signal levels continue to decrease, a new set of low-voltage-level translators are needed. This is the reason why the TXB030x family of low-voltage auto-direction sensing translators were made.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver. The TXB030x family is designed so that the OE input circuit is supplied by $V_{\rm CCA}$. The devices are fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



TXB030x functional block diagram.

Bidirectional Auto Direction Sensing Translators

TXB010x

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXB010x

Key Features

- Optimized for push-pull drivers
- 100 Mbps max data rate transfer
- V_{CC} isolation feature
- OE input circuit referenced to V_{CCA}
- Low power consumption
- I_{OFF} supports operation in partialpower-down mode
- 1.2 V to 3.6 V on A-port and 1.65 V to 5.5 V on B-port (V_{CCA} ≤ V_{CCB})

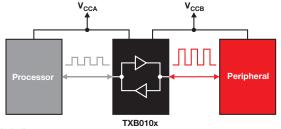
Applications

- Cell phones
- SD/SDIO level translation
- SPI and GPIO level translation

These non-inverting translators use two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 1.65 V to 5.5 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes. V_{CCA} should not exceed V_{CCB} .

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state. This device is fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.



TXB010x functional block diagram.



Auto-Direction Sensing Translators for Open Drain Applications

Bidirectional Auto Direction Sensing Translators for Open Drain Applications with 0.9 V Support TXS030x

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS030x

Key Features

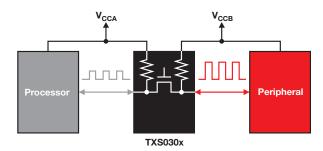
- Optimized for open-drain applications
- Fully symmetric supply voltages:
 0.9 V to 3.6 V on both A-port and
 B-port
- V_{CC} isolation feature if either V_{CC} input is at GND, all outputs are in the high-impedance state
- OE input circuit referenced to V_{CCA}
- Low power consumption, 5-μA max I_{CC}
- 8-kV Human-Body Model (HBM)

Applications

- Cell phones
- Tablets
- Portable GPS devices
- Bluetooth® headsets
- General portable consumer applications

These two-bit non-inverting translators uses two separate configurable power-supply rails. The A port is designed to track V_{CCA} . V_{CCA} accepts any supply voltage from 0.9 V to 3.6 V. The B port is designed to track V_{CCB} . V_{CCB} accepts any supply voltage from 0.9 V to 3.6 V. This allows for low-voltage bidirectional translation between 1-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V and 3.3-V voltage nodes.

For the TXS0302, when the output-enable (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver. The TXS0302 is designed so that the OE input circuit is supplied by $V_{\rm CCA}$. This device is fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



TXS030x functional block diagram.

Bidirectional Auto Direction Sensing Translators for Open Drain Applications

TXS010x

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS010x

Key Features

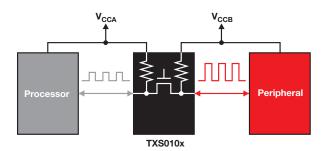
- Works with both open-drain and push-pull drivers
- Max data rates:24 Mbps (push-pull)
 - o 2 Mbps (open-drain)
- 1.65 V to 3.6 V on A-port and 2.3 V to 5.5 V on B-port (V_{CCA} ≤ V_{CCB})
- No power supply sequencing required
- IEC 61000-4-2 ESD protection on B-port for "E" suffix devices

Applications

- · Cell phones
- I2C level translation
- MMC and SIM card level translations.

These non-inverting translators use two separate configurable power-supply rails. The A port is designed to track $V_{\rm CCA}$. $V_{\rm CCA}$ accepts any supply voltage from 1.65 V to 3.6 V. The B port is designed to track $V_{\rm CCB}$. $V_{\rm CCA}$ must be less than or equal to $V_{\rm CCB}$. $V_{\rm CCB}$ accepts any supply voltage from 2.3 V to 5.5 V. This allows for low-voltage bidirectional translation between any of the 1.8-V, 2.5-V, 3.3-V, and 5-V voltage nodes.

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.



TXS010x functional block diagram.

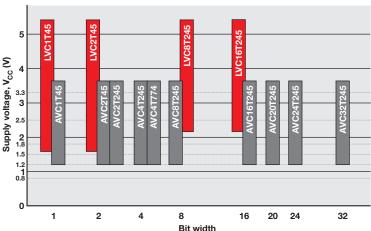


Configurable Translators with Direction Control Portfolio

Key Features

- Fully configurable rails each V_{CC} rail is fully configurable from 1.2 V to 3.6 V (AVCxT devices) and from 1.65 V to 5.5 V (LVCxT devices)
- No power-up sequencing either V_{CC} can be powered up first (AVCxT and LVCxT devices only)
- Standby mode when one V_{CC} is switched off, all I/O ports are placed in the HiZ mode (AVCxT and LVCxT devices only).

TI translators with direction control are designed for asynchronous communication between two buses or devices operating at different supply voltages: V_{CCA} to interface with the A side and V_{CCB} to interface with the B side. These devices are available in a variety of bit widths and cover nearly every supply-voltage node in use today. They are flexible, easy to use and can translate bidirectionally (up-translate and down-translate), which makes them an ideal choice for most level-translation applications.



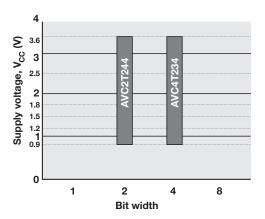
Direction-control translators.

Configurable Unidirectional Translators Portfolio

Key Features

- Unidirectional architecture eliminates the direction control pin saving precious GPIO pins on the processor
- Fully configurable rails from 0.9 V to 3.6 V enable support of 1.0 V nodes used by the most advanced processors
- Ioff circuitry prevents damaging current backflow in power-down mode

TI unidirectional translators are designed for asynchronous communication between B-port inputs and A-port outputs operating at different supply voltages: V_{CCA} to interface with the A side and V_{CCB} to interface with the B side. These devices cover the most advanced (1.0V and 1.2V) supply-voltage nodes in use today and are fully configurable from 0.9V to 3.6V on both A-port and B-port sides. These devices are fully specified for partial power down applications and use loff circuitry that prevents damaging current backflow in power-down mode. These features make these translators an ideal choice for battery powered portable electronics applications.





Configurable Translators with Direction Control

Dual-Supply Bus Transceiver with Configurable Voltage Translation and 3-State Outputs SN74AVCxT45/245

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/SN74AVCxT45/245

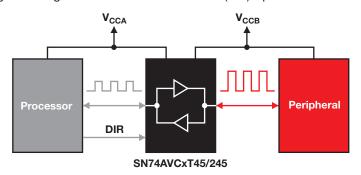
Key Features

- 380 Mbps max data rate
- Control input levels, V_{IH}/V_{IL}, are referenced to V_{CCA} voltage
- Fully configurable dual-rail design allows each port to operate over full 1.2-V to 3.6-V power-supply range
- I_{OFF} supports operation in partialpower-down mode

Applications

- Handsets
- PDAs
- Computing
- Smartphones

These devices are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input.



SN74AVCxT45/245 functional block diagram.

Dual-Supply Bus Transceiver with Configurable Voltage Translation and 3-State Outputs SN74LVCxT45/245

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/SN74LVCxT45/245

Key Features

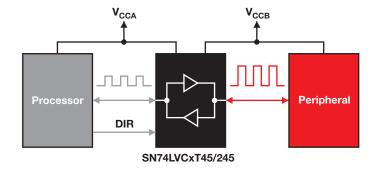
- Control input levels, V_{IH}/V_{IL}, are referenced to V_{CCA} voltage
- Fully configurable dual-rail design allows each port to operate over full 1.65-V to 5.5-V power-supply range
- I_{OFF} supports operation in partialpower-down mode

Applications

- Portables
- Telecom
- Computing
- Translation from 3.3 V to 5 V

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, then both ports are in the high-impedance state. To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



SN74LVCxT45/245 functional block diagram.



Configurable Unidirectional Translators

4-Bit, Dual-Supply, Non-Inverting Bus Translator

SN74AVC4T234

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/SN74AVC4T234

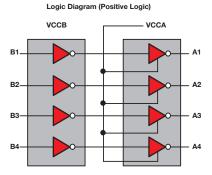
Key Features

- 380 Mbps max data rate
- Wide operating V_{CC} range of 1.2 V to 3.6 V
- 3.6-V I/O tolerant to support mixedmode signal operation
- Input-disable feature allows floating input conditions
- Input hysteresis allows slow input transition and better switching noise immunity at input

Applications

- Handsets
- PDAs
- Computing
- Smartphones

This 4-bit non-inverting bus transceiver uses two separate configurable power-supply rails to enable asynchronous communication between B-port inputs and A-port outputs. The A port is designed to track $V_{\rm CCA}$ while the B port is designed to track $V_{\rm CCB}$. Both $V_{\rm CCA}$ and $V_{\rm CCB}$ are configurable from 1.2 V to 3.6 V. The SN74AVC4T234 solution offers the industry's low-power needs in battery-powered portable applications by ensuring both a very low static and dynamic power consumption across the entire $V_{\rm CC}$ range of 1.2 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity. This device is fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The $V_{\rm CC}$ isolation feature ensures that if either $V_{\rm CC}$ input is at GND, then A-side ports are in the high-impedance state.



Logic diagram (positive logic).

2-Bit, Dual-Supply, Unidirectional Translator with Output Enable SN74AVC2T244

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/SN74AVC2T244

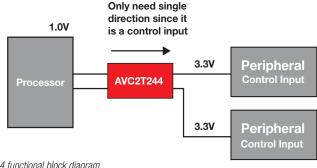
Key Features

- Wide operating V_{CC} range of 0.9 V to 3.6 V
- Output enable pin allows user to disable outputs to reduce power consumption
- 380 Mbps max data rate
- Input hysteresis allows slow input transition and better switching noise immunity at input
- 4.5 V tolerant I/O to support mixed signal mode operation

Applications

- Handsets
- PDAs
- Computing
- Smartphones

This 2-bit unidirectional translator uses two separate configurable power-supply rails to enable asynchronous communication between B-port inputs and A-port outputs. The A port is designed to track $V_{\rm CCA}$ while the B port is designed to track $V_{\rm CCB}$. Both $V_{\rm CCA}$ and $V_{\rm CCB}$ are configurable from 0.9 V to 3.6 V. The SN74AVC2T244 offers an output enable pin to disable outputs that reduces power consumption significantly in power down mode. It offers very low static and dynamic power consumption across the entire $V_{\rm CC}$ range of 0.9 V to 3.6 V, making it the ideal translator for battery powered portable electronics applications.



SN74AVC2T244 functional block diagram.



Application Specific Translators

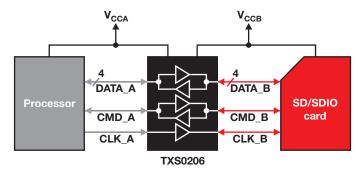
SD Card, Memory Stick, and MMC Voltage-Translation Transceivers with ESD Protection and EMI Filtering TXS0206 and TXS0206-29

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS0206; www.ti.com/product/TXS0206-29

Key Features

- Voltage-translation transceiver for memory card interfaces (SD, Mini SD, MMC)
- Fully configurable dual-voltage supply architecture with both V_{CCA} and V_{CCB} operating range of 1.1 V to 3.6 V
- Six bidirectional channels capable of passing 60 Mbps data rates with 3 ns typical prop-delay
- No direction control needed on data/command paths
- Integrated pull-up resistors on card-side I/Os per SD specification
- SDIO-compliant integrated smart pull-up resistors — enables output drivers to maintain modest DC-bias current sourcing capabilities while maintaining low static power consumption

Memory card standards recommend high-ESD protection for devices that connect directly to the external memory card. To meet this need, these devices incorporate ±8-kV Contact Discharge protection on the card side.



TXS0206 functional block diagram.

Applications

- Mobile phones
- PDAs
- · Digital cameras
- Personal media players
- Camcorders
- · Set-top boxes

Interchip USB Voltage Level Translator

TXS0202

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS0202

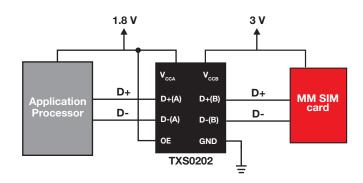
Key Features

- Auto-direction sensing translator
- Voltage range of 1.65-3.6 V
- I_{off} supports partial-power-down mode operation
- · Actively detects the status of the host and peripheral and will determine which of the four various modes is desired
- · No direction signal control needed
- · Works with legacy to next-generation processors and peripherals
- This is done without any need for direction control, external FETs, or external pull up resistors

Applications

- Handsets
 - Smartphone
 - Multimedia
 - Feature
- **Tablet**
- Portable gaming devices

The TXS0202 is a two-bit voltage level translator optimized for use in Interchip USB (IC-USB) applications. V_{CCA} and V_{CCB} can each operate over the full range of 1.65 V to 3.6 V. The device has been designed to maintain cross-over skew to be less than 1 ns. The device has integrated pull-ups and pull-down resistors to aid in the protocol communication between a host and a peripheral. The translator is a buffered auto-direction sensing type translator. When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.



TXS020x functional block diagram.



Application Specific Translators

Dual-supply SIM Card Translator and 2:1 Multiplexer

TXS02326

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS02326

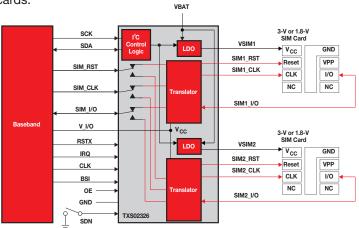
Kev Features

- Dual-supply translator with voltage range of 1.7 V to 3.6 V
- 2:1 multiplexer function enables the use of a single SIM card interface to control two SIM cards
- Integrated dual-LDOs enable support of 1.8 V and 2.95 V SIM card standards
- Available in popular 24-pin QFN package

Applications

· Cell phones

The TXS02326 is a dual-supply SIM card solution for interfacing wireless baseband processors with two SIM cards. The 2:1 multiplexer function extends the single SIM card interface to support two SIM cards. The dual-supply voltage translation function supports 1.7 V to 3.3 V range on the processor side and either 1.8 V or 2.95 V on the SIM card side. The two SIM card interface standards, Class-B (2.95 V) and Class-C (1.8 V) are supported by two integrated low-dropout (LDO) voltage regulators with selectable outputs. An integrated 400 kb/s I²C interface offers several configuration options, including safe power-down of the two SIM cards.



Interfacing with SIM card.

1.8 V and 3 V SIM Card Power Supply and Voltage Translator

TXS4555

Get samples, data sheets, EVMs and app reports at: www.ti.com/product/TXS4555

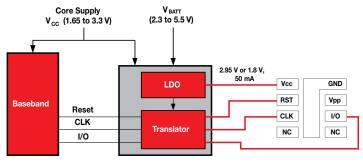
Key Features

- Dual-supply translator with voltage range of 1.65 V to 3.3 V
- Integrated LDO accepts battery voltage from 2.3 V to 5.5 V and generates 1.8 V or 2.95 V output
- Proper shutdown sequence prevents data corruption in case of accidental phone shutdown
- Available in tiny 16-pin (9mm²) and 12-pin (3.5mm²) QFN packages

Applications

Cell phones

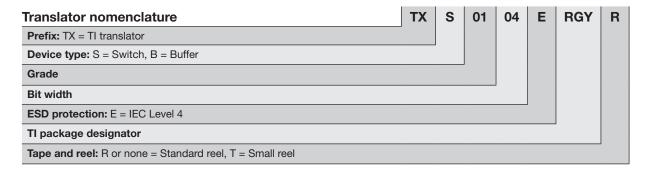
The TXS4555 is a dual-supply SIM card solution for interfacing a wireless baseband processor with any Class-B (2.95 V) or Class-C (1.8 V) SIM card. The dualsupply voltage translation function supports 1.65 V to 3.3 V range on the processor side and accepts any battery voltage between 2.3 V and 5.5 V to generate a constant 1.8 V or 2.95 V output on the SIM card side. A dedicated low-dropout (LDO) voltage regulator with selectable output is used to generate the desired SIM card voltage. Proper shutdown sequence for the SIM card signals helps in prevention of corruption of data during accidental shutdown of the phone.

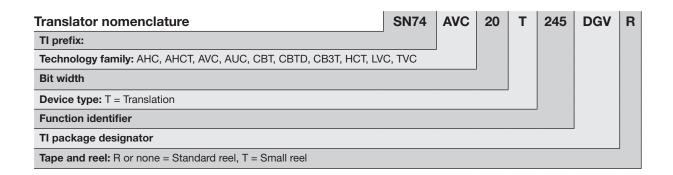


Interfacing with SIM card.

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Translator Nomenclature





Selection Tables

	V _{CC} Min. t	o Max. (V)		V _{CCA} (V) V _{CCB} (V)																	
Device	V _{CCA}	V _{CCB}	0.9	1.2	1.5	1.65	1.8	2.5	2.7	3.3	5	0.9	1.2	1.5	1.65	1.8	2.5	2.7	3.3	5	Smallest package
Application Sp	ecific																				
CF4320H	1.65 to V _{CCB}	3 to 5.5					~	~	~	~	~								~	~	114-ball LFBGA
SN74AVCA406L	1.2 to 3.6	1.2 to 3.6		~	~		~	~	~	~			~	~		~	~	~	~		20-ball VFBGA
SN74AVC2T872	1.1 to 3.6	1.1 to 3.6		~	~		~	~	~	~			~	~		~	~	~	~		12-ball WCSP
SN74AVC6T622	1.2 to 3.6	1.2 to 3.6		~	~		~	~	~	~			~	~		~	~	~	~		20-ball UFBGA
TWL1200	1.1 to 3.6	1.1 to 3.6		~		~	~	~	~	~					~	~	~	~	~		YFF
TXS0202	1.65 to 3.6	1.65 to 3.6				~	~	~	~	~					~	~	~	~	~		YZP
TXS0206	1.1 to 3.6	1.1 to 3.6		~	~		~	~	~	~			~	~		~	~	~	~		20-ball WCSP
TXS0206-29	1.1 to 3.6	5V Max VBAT		~		~	~	~	~	~											YFP
TXS02612	1.1 to 3.6	1.1 to 3.6		~	~		~	~	~	~			~	~		~	~	~	~		24-ball VFBGA
Application Sp	ecific: SIM (Card Transl	ators																		
TXS4555	1.65 to 3.3	2.3 to 5.5				~	~	~	~	~						~		2.95			RUT
TXS02326	1.7 to 3.3	2.3 to 5.5				~	~	~								~		2.95			RGE
TXS02326A	1.7 to 3.3	2.3 to 5.5				~	~	~								~		2.95			RGE
TXS02324	1.7 to 3.3	2.3 to 5.5				~	~	~								~		2.95			RUK
TXS4558	1.7 to 3.3	2.3 to 5.5					~	~	~	~						~		2.95			RUT

¹Bus-hold option available

Preview products are listed in bold blue.

Selection Tables (Continued)

	V _{CC} Min. to Max. (V)						V _{CC}	(V)			V _{CCB} (V)										
Device	V _{CCA}	V _{CCB}	0.9	1.2	1.5	1.65	1.8	2.5	2.7	3.3	5	0.9	1.2	1.5	1.65	1.8	2.5	2.7	3.3	5	Smallest package
1-Bit																					
SN74AVC1T45 ¹	1.2 to 3.6	1.2 to 3.6		~	~		V	V	V	~			~	~		V	V	~	~		6-ball NanoStar [™] /NanoFree [™]
SN74LVC1T45	1.65 to 5.5	1.65 to 5.5					~	V	~	~	V					V	~	~	~	~	6-ball NanoStar/NanoFree
TXB0101	1.2 to 3.6	1.65 to 5.5		~	~		~	V	~	~						V	V	V	~	~	6-ball NanoFree
TXS0101	1.65 to 3.6	2.3 to 5.5					~	V	~	~							V	V	~	~	6-ball NanoFree
2-Bit																					
SN74AVC2T45 ¹	1.2 to 3.6	1.2 to 3.6		~	~		V	V	V	~			~	~		V	V	V	~		8-ball NanoStar/NanoFree
SN74AVC2T244	0.9 to 3.6	0.9 to 3.6	~	~	~	V	~	V	~	~		~	~	~	~	V	V	V	~		8-pin μQFN
SN74LVC2T45	1.65 to 5.5	1.65 to 5.5					V	V	~	V	V					1	1	1	V	~	8-ball NanoStar/NanoFree
SN74LVC2T245	1.2 to 3.6	1.2 to 3.6		~	~		V	V	~	~			~	~		~	~	~	~		10-pin QFN
TXB0102	1.2 to 3.6	1.65 to 5.5		~	~		V	V	~	V						1	V	1	V	~	8-ball NanoFree
TXB0302	0.9 to 3.6	0.9 to 3.6	V	~		V	V	V	~	~		~	~		~	~	~	~	V		RGE
TXS0102	1.65 to 3.6	2.3 to 5.5					V	V	~	V							V	1	V	~	8-ball NanoFree
TXS0302	0.9 to 3.6	0.9 to 3.6		V	~		V	V		~			V	~		~	V		V		8-pin, YFP, DQE and DQM
4-Bit																					
SN74AVC4T234	1.1 to 3.6	1.1 to 3.6		V		V	V	V	~	V			~		~	~	V	~	V		ZSU
SN74AVC4T245 ¹	1.2 to 3.6	1.2 to 3.6		~	~		V	V	~	V			~	1		1	V	1	V		16-pin QFN
SN74AVC4T774	1.2 to 3.6	1.2 to 3.6		~	~		V	V	~	~			V	V		~	V	V	V		16-pin QFN
TXB0104	1.2 to 3.6	1.65 to 5.5		V	~		V	V	~	V						1	V	1	V	~	12-ball UFBGA
TXB0304	0.9 to 3.6	0.9 to 3.6	V	~		V	V	V	~	~		~	~		~	~	~	~	V		RSV
TXS0104E	1.65 to 3.6	2.3 to 5.5					~	V	~	~							~	~	~	~	12-ball UFBGA
6-Bit																					
TXB0106	1.2 to 3.6	1.65 to 5.5		~	~		V	V	V	V						~	~	~	V	~	16-pin QFN
8-Bit																					
SN74AVC8T245 ¹	1.2 to 3.6	1.2 to 3.6		~	~		V	V	V	~			~	~		~	~	~	V		24-pin QFN
SN74LVC8T245 ¹	1.65 to 5.5	1.65 to 5.5					V	V	~	~	~					~	~	~	~	~	24-pin QFN
TXB0108	1.2 to 3.6	1.65 to 5.5		V	~		~	V	V	~						~	~	~	~	~	20-ball VFBGA
TXS0108E	1.65 to 3.6	2.3 to 5.5					~	V	~	~							V	V	~	~	20-ball VFBGA
16-Bit																					
SN74AVC16T245 ¹	1.2 to 3.6	1.2 to 3.6		V	~		~	V	V	~			~	~		~	~	~	~		56-ball VFBGA
SN74LVC16T245 ¹	1.65 to 5.5	1.65 to 5.5					~	V	V	~	V					~	~	~	~	~	56-ball VFBGA
20-Bit																					
SN74AVC20T245 ¹	1.2 to 3.6	1.2 to 3.6		V	~		V	V	~	~			~	~		~	~	~	~		56-ball VFBGA
24-Bit																					
SN74AVC24T245 ¹	1.2 to 3.6	1.2 to 3.6		V	V		V	V	V	V			V	~		V	V	V	V		83-ball LFBGA
32-Bit																					
SN74AVC32T245 ¹	1.2 to 3.6	1.2 to 3.6		V	V		~	V	V	~			~	~		~	V	V	V		96-ball LFBGA

¹Bus-hold option available

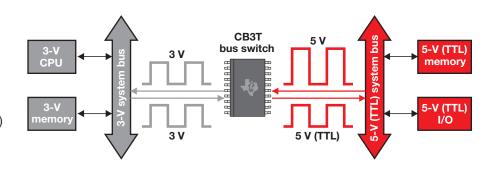
Preview products are listed in **bold blue**.

Additional Translators

FET Switches

Devices from TI's CBT, CBTD, CB3T and TVC families can be used in leveltranslation applications. The diagram shows a CB3T bus switch interfacing a 3-V bus with a 5-V (TTL) bus. The CB3T device down-translates the signals from the 5-V bus to 3-V levels.

No translation is necessary to transfer signals from the 3-V bus to the 5-V (TTL) bus, since the V_{OH} level from the CB3T switch is greater than the required V_{II} of the 5-V (TTL) devices connected to the 5-V bus.



FET switch for translation.

Advantage

· Fast propagation delays

Overvoltage-Tolerant Devices and TTL-Compatible Inputs and **Open-Drain Output Devices**

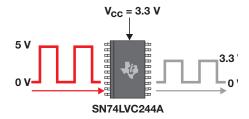
Overvoltage-Tolerant Devices

Devices with overvoltage-tolerant inputs can be used to perform down-translation as shown in the diagram. Logic families with overvoltage-tolerant inputs include:

- AHC LV-A
- AUC • LVC
- AVC

Advantages

- · Only one supply voltage needed
- Broad portfolio of AHC, AUC, AVC, LV-A and LVC devices



Down-translation.

Devices with TTL-Compatible Inputs

Up-translation from 3.3-V LVCMOS/ LVTTL to 5-V CMOS levels can be achieved with logic devices from TI's HCT, AHCT, ACT and AUP families.

Advantages

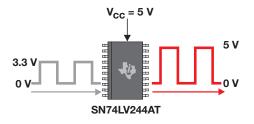
- · Only one supply voltage needed
- Broad portfolio of HCT, AHCT, ACT and AUP devices

Devices with Open-Drain Outputs

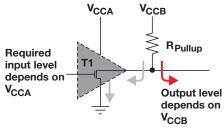
Devices with open-drain outputs can be used to perform both up-translation and down-translation. The output voltage is determined by V_{CCB}. This output level can be higher than V_{CCA} (up-translation) or lower than V_{CCA} (down-translation).

Advantages

 Flexibility in translating to/from a variety of voltage nodes



TTL up-translation.



Translation with open-drain buffers.

Resources



Sample Requests and Quality Assurance

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